

**IN THE CLAIMS:**

Please amend the claims as follows:

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Claim 1 (Currently Amended): An optical pickup device, comprising;  
a lead frame package having a sub-mount, a laser source mounted on said sub-mount to  
emit ~~and emitting~~ a laser beam, a reflective element to reflecting said beam, a transmission-type  
refraction grating to divide ~~dividing~~ said beam into a plurality of beams including a main beam  
and two sub beams, which are incident to an optical medium, and a hologram optical element to  
diffract ~~diffracting~~ the beams reflected from an optical medium, said lead frame package having  
an opening ~~communicating with an outside of said lead frame package~~; and  
a detecting unit having a substrate and a photo detector mounted on said substrate, said  
substrate ~~detecting unit~~ located external to ~~being separate from~~ said lead frame package.

Claim 2 (Currently Amended): The device of claim 1, wherein said detecting unit is  
disposed at ~~within~~ said opening of said lead frame package, said detecting unit fixed to said lead  
frame package after moved ~~moving~~ to a position to receive said beams diffracted from said  
hologram optical element.

Claim 3 (Currently Amended): The device of claim 1, wherein said detecting unit is  
~~being~~ a chip-on-board photo diode package.

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Claim 4 (Currently Amended): The device of claim 1, wherein said detecting unit is being a flip-chip package.

Claim 5 (Currently Amended): The device of claim 1, wherein said reflective element is being a mirror.

Claim 6 (Currently Amended): An optical pickup device, comprising:  
a lead frame package having a sub-mount, a light source mounted on said sub-mount and emitting a laser beam, a transmission-type diffraction grating element dividing said beam into a main and two sub beams, which are incident to an optical medium, and a hologram optical element diffracting said beams reflected from said optical medium, said lead frame package having an opening ~~communicating with an outside of said lead frame package~~; and  
a detecting unit having a substrate and a photo detector mounted on said substrate, said substrate detecting unit located external to ~~being separate from~~ said lead frame package.

Claim 7 (Currently Amended): The device of claim 6, wherein said detecting unit is disposed at within said opening of said lead frame package, said detecting unit fixed to said lead frame package ~~after moving to a position within said opening to receive said beams diffracted from said hologram optical element.~~

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Claim 8 (Currently Amended): The device of claim 6, wherein said detecting unit is being a chip-on-board photo diode package.

Claim 9 (Currently Amended): The device of claim 6, wherein said detecting unit is being a flip-chip package.

Claim 10 (Currently Amended): An optical pickup device, comprising:  
a lead frame package having a sub-mount, a light source mounted on the [[a]] sub-mount to emit ~~and emitting~~ a laser beam, a reflecting element to direct ~~directing~~ said beam onto an optical medium, and a hologram optical element to diffract ~~diffracting~~ said beam reflected from said optical medium, said lead frame package having an opening ~~communicating with an outside of said lead frame package~~; and

a detecting unit having a substrate and a photo detector mounted on said substrate, said substrate ~~detecting unit~~ located external to ~~being separate from~~ said lead frame package.

Claim 11 (Currently Amended): The device of claim 10, wherein said detecting unit is disposed at ~~within~~ said opening of said lead frame package, said detecting unit fixed to said lead frame package ~~after moving to a position within said opening to receive said beams diffracted from said hologram optical element.~~

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Claim 12 (Currently Amended); The device of claim 10, wherein said reflective element is being a reflection-type diffraction grating element dividing said beam emitted from said light source into a plurality of beams including main and two sub beams reflected toward said optical medium.

Claim 13 (Currently Amended); The device of claim 10, wherein said detecting unit is being a chip-on-board photo diode package.

Claim 14 (Currently Amended); The device of claim 10, wherein said detecting unit is being a flip-chip package.

Claim 15 (Currently Amended): The device of claim 10, wherein said reflective element is being a mirror.

Claim 16 (Currently Amended): An optical pickup device, comprising:  
a lead frame package having a sub-mount, a light source mounted on said sub-mount and emitting a laser beam which is incident to and reflected from an optical medium, and a hologram optical element diffracting said beams reflected from and optical medium, said lead frame package having an opening ~~communicating with both said hologram optical element and an outside of said lead frame package;~~ and

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a detecting unit having a substrate and a photo detector mounted on said substrate, said substrate detecting unit located external to being separate from said lead frame package.

Claim 17 (Currently Amended): The device of claim 16, wherein said detecting unit disposed at within said opening of said lead frame package, said detecting unit fixed to said lead frame package after moved moving to a position at within said opening to receive said beams diffracted from said hologram optical element.

Claim 18 (Currently Amended): The device of claim 16, wherein said detecting unit is being a chip-on-board photo diode package.

Claim 19 (Currently Amended): The device of claim 16, wherein said detecting unit is being a flip-chip package.

Claim 20 (Cancelled).

Claim 21 (Currently Amended): A process for manufacturing [[in]] an optical pickup device, comprising the steps of:

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providing a lead frame package having a sub-mount, a light source mounted said sub-mount and emitting a laser beam which is incident to and reflected from an optical medium, and a hologram optical element diffracting said beams reflected from said optical medium, said lead frame package having an ~~opening communicating with both said hologram optical element and an outside of said lead frame package;~~

providing a detecting unit having a substrate and a photo detector mounted on said substrate, said substrate detecting unit located external to ~~being separate from~~ said lead frame package;

locating said detecting unit at ~~within~~ said opening of said lead frame package;

moving said detecting unit with respect to said lead frame package; and

fixing said detecting unit to said lead frame package.

Claim 22 (Currently Amended): The process of claim 21, further comprising the steps of:

monitoring a signal obtained by ~~obtaining~~ said photo detector during movement of said detecting unit with respect to said lead frame package; and

fixing said detecting unit to said lead frame package when said signal is in a predetermined range.

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Claim 23 (New): The device of claim 10, wherein said reflective element is a reflection-type diffraction grating element that is mounted within the lead frame package.

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